

## MTW23N25E-VB Datasheet N-Channel 250 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)		
250	0.040 at V <sub>GS</sub> = 10 V	60	95		
250	0.045 at V <sub>GS</sub> = 6 V	55	95		

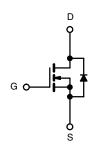
### **FEATURES**

- Trench Power MOSFETS
- 175 °C Junction Temperature
- New Low Thermal Resistance Package
- Compliant to RoHS Directive 2002/95/EC



#### **APPLICATIONS**

• Industrial



N-Channel MOSFET

TO-247AC
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Top View

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	250	٧			
Gate-Source Voltage	V <sub>GS</sub>	± 30	V			
Continuous Drain Current (T <sub>J</sub> = 175 °C)	T <sub>C</sub> = 25 °C	I-	60	A		
	T <sub>C</sub> = 125 °C	I <sub>D</sub>	35			
Pulsed Drain Current	I <sub>DM</sub>	200				
Avalanche Current	I <sub>AR</sub>	35				
Repetitive Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AR</sub>	61	mJ		
Maximum Dawar Discipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	300 <sup>b</sup>	w		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	- FD	3.75			
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	0.5	C/VV		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min .	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	250			٧	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 30 \text{ V}$			± 250	nA	
		V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V			1	μА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50		
		V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	70			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A		0.040		- Ω	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 125 °C		0.091			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 30 A, T <sub>J</sub> = 175 °C		0.123			
		V <sub>GS</sub> = 6 V, I <sub>D</sub> = 25 A		0.045			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 30 A		70		S	
Dynamic <sup>b</sup>	<b>!</b>						
Input Capacitance	C <sub>iss</sub>			5000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		300			
Reverse Transfer Capacitance	C <sub>rss</sub>			170			
Total Gate Charge <sup>c</sup>	Qg			95	140		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>DS</sub> = 125 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 45 A		28		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			34			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	1.6			Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			22	35		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_{L} = 2.78 \Omega$		220	330		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 45 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		40	60	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			145	220		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C) <sup>b</sup>		_			
Continuous Current	I <sub>S</sub>	l <sub>S</sub>			45	^	
Pulsed Current	I <sub>SM</sub>				70	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 45 A, V <sub>GS</sub> = 0 V		1	1.5	٧	
Reverse Recovery Time	t <sub>rr</sub>			150	225	ns	
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 45 A, di/dt = 100 A/μs		12	18	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.9	2	μС	

#### Notes

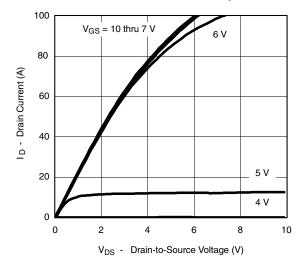
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

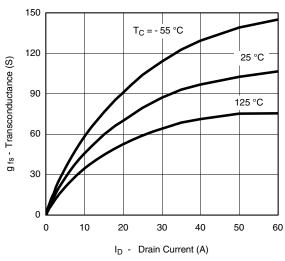
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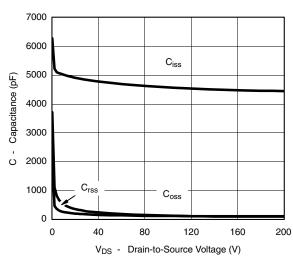
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



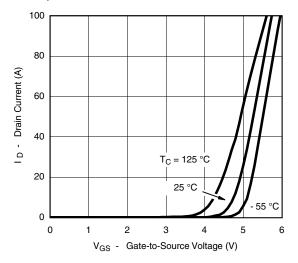




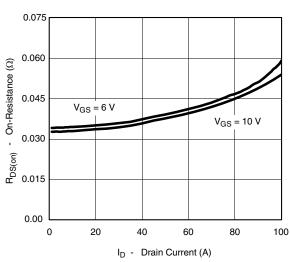
#### Transconductance



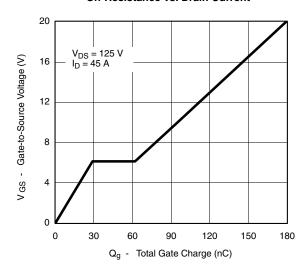
Capacitance



#### **Transfer Characteristics**



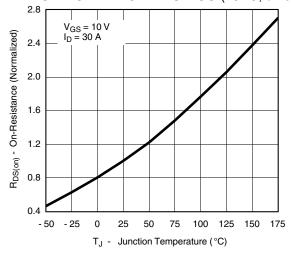
#### On-Resistance vs. Drain Current



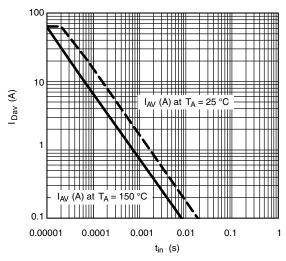
**Gate Charge** 



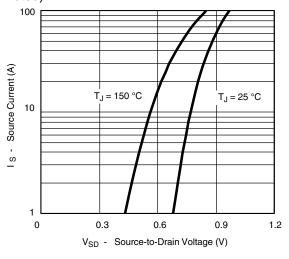
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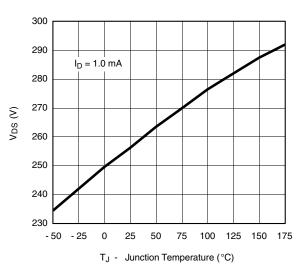
#### On-Resistance vs. Junction Temperature



**Avalanche Current vs. Time** 



#### Source-Drain Diode Forward Voltage

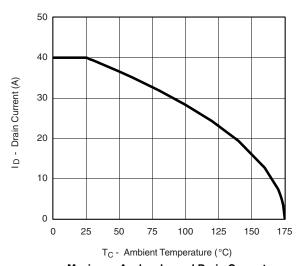


**Drain Source Breakdown vs. Junction Temperature** 

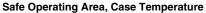
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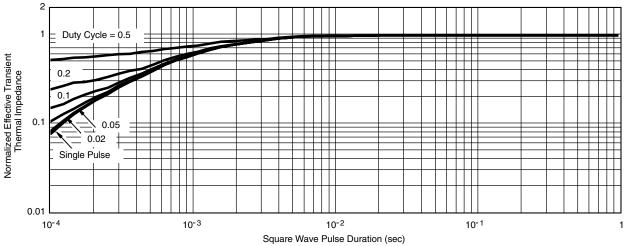


#### THERMAL RATINGS



Maximum Avalanche and Drain Current vs. Case Temperature





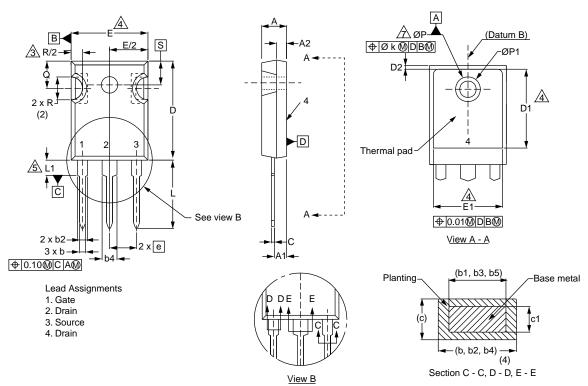
Normalized Thermal Transient Impedance, Junction-to-Case

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## **TO-247AC (High Voltage)**



	MILLIMETERS			HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	
E1	13.72	-	0.540	-	
е	5.46 BSC		0.215 BSC		
Øk	0.254		0.010		
L	14.20	16.25	0.559	0.640	
L1	3.71	4.29	0.146	0.169	
N	7.62	7.62 BSC 0.30		0 BSC	
ØΡ	3.51	3.66	0.138	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51	5.51 BSC 0.217 BSC		BSC	

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